

ABSTRACT OF THE INVENTION

The invention relates to a process of forming a thermal interface that employs carbon nanotubes to reduce thermal resistance between an electronic device and a cooling solution. Bundles of aligned nanotubes receive injected
5 polymeric material to produce a polymeric/carbon composite which is then placed between the electronic device and a heat sink or other cooling solution.

"Express Mail" mailing label number: EL833034105US

Date of Deposit: December 20, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.